

Seat No.	
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B.E. (Mechanical) (Part - II) (Semester - VIII) (Old)

Examination, May- 2017

MICRO ELECTRO MECHANICAL SYSTEM (Elective - III)

Sub. Code: 49421

Day and Date : Wednesday, 03- 05 - 2017

Total Marks : 100

Time : 2.00 p.m. to 5.00 p.m.

- Instructions :**
- 1) Attempt any three questions from each section.
 - 2) Figures to the right indicate full marks.

SECTION-I

- Q1) a)** What is inertia sensor? How it is used in air bag deployment system. [10]
- b) Differentiate Microsystems and microelectronics. [8]
- Q2) a)** What is photolithography? Describe in detail. [8]
- b) Explain procedure to creat a polysilicon cantilever beam on Si base. [8]
- Q3) a)** Explain in detail etching processes in detail. [8]
- b) Compare Ion implantion with diffusion process along with working principles. [8]
- Q4) a)** What is Czocharalski method for producing single crystal Si. [8]
- b) How piezoresistors and piezoelectric crystals are used in MEMS. [8]

SECTION-II

- Q5) a)** What are optical sensors? [10]
- b) What are the ways of transducing the deformation of diaphragm to electric output signal. [8]

P.T.O.

- Q6) a) What are the applications of MEMS in microfluidics. [8]
b) What are design considerations in MEMS. [8]
- Q7) a) Explain surface bonding and wire bonding. [8]
b) What are the techniques for pumping in Microfluidics. [8]
- Q8) a) Explain electrostatic actuation principles along with examples. [8]
b) What is the working principles of microgripper and micropumps. [8]

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